

# TCA6408A-Q1 具有中断输出的低电压 8 位 I<sup>2</sup>C 和 SMBus I/O 扩展器

## 1 特性

- I<sup>2</sup>C 至并行端口扩展器
- 1.65V 至 3.6V 工作电源电压范围
- 支持 1.8V、2.5V、3.3V I<sup>2</sup>C 总线和 P 端口之间进行双向电平转换和通用输入/输出 (GPIO) 扩展
- 低待机功耗
- 400kHz 快速 I<sup>2</sup>C 总线
- 硬件寻址引脚允许同一 I<sup>2</sup>C/SMBus 总线存在两个 TCA6408A-Q1 器件
- 低电平有效复位 ( $\overline{\text{RESET}}$ ) 输入
- 开漏低电平有效中断 ( $\overline{\text{INT}}$ ) 输出
- 输入和输出配置寄存器
- 极性反转寄存器
- 内部加电复位
- 在所有通道均被配置为输入的情况下加电
- 在加电时无毛刺脉冲
- SCL/SDA 输入端上的噪声滤波器
- 具有最大高电流驱动能力的锁存输出，适用于直接驱动 LED
- 锁存性能可达 100mA，符合 AEC Q100-004 标准
- 施密特触发器操作支持在串行时钟 (SCL) 和串行数据 (SDA) 输入实现缓慢输入转换并提升开关噪声抗扰度
- 静电放电 (ESD) 保护
  - 2000V 人体模型 (Q100-002)
  - 1000V 带电器件模型 (Q100-011)

## 2 应用

- 车用信息娱乐
- 高级驾驶员辅助系统 (ADAS)
- 汽车车身电子设备
- 混合动力汽车 (HEV)、电动汽车 (EV) 和动力传动
- 工业、工厂和楼宇自动化
- 测试和测量
- 电子销售点 (EPOS)

## 3 说明

TCA6408A-Q1 是一款 16 引脚器件，可为两线双向 I<sup>2</sup>C 总线（或 SMBus）协议提供 8 位通用并行输入/输出 (I/O) 扩展。在器件运行过程中，I<sup>2</sup>C 总线侧 (V<sub>CCI</sub>) 和 P 端口侧 (V<sub>CCP</sub>) 均可由电压介于 1.65V 至 3.6V 之间的电源供电。这使得 TCA6408A-Q1 能够在 SDA/SCL 侧（电源电平在此逐渐降低以节省功率）与下一代微处理器和微控制器相连。与微处理器和微控制器的降压电源相比，部分 PCB 组件（例如 LED）仍由高电压电源供电。

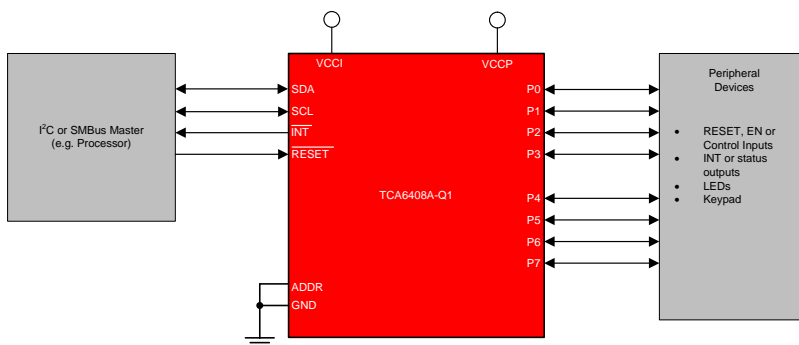
该器件支持 100kHz（标准模式）和 400kHz（快速模式）时钟频率。当开关、传感器、按钮、LED、风扇等设备需要额外使用 I/O 时，I/O 扩展器（如 TCA6408A-Q1）可提供简易解决方案。

### 器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸 (标称值)
TCA6408A-Q1	TSSOP (16)	5.00mm x 4.40mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。

### 简化电路原理图



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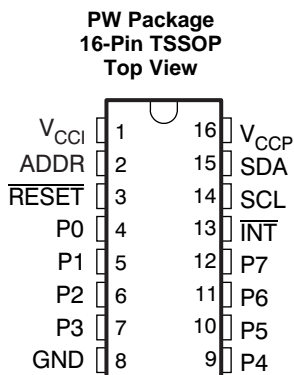
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## 4 修订历史记录

日期	修订版本	注释
2016 年 9 月	*	最初发布版本。

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
ADDR	2	I	Address input. Connect directly to V <sub>CCP</sub> or ground
GND	8	—	Ground
INT	13	O	Interrupt output. Connect to V <sub>CCI</sub> through a pull-up resistor
P0	4	I/O	P-port input-output (push-pull design structure). At power on, P0 is configured as an input
P1	5	I/O	P-port input-output (push-pull design structure). At power on, P1 is configured as an input
P2	6	I/O	P-port input-output (push-pull design structure). At power on, P2 is configured as an input
P3	7	I/O	P-port input-output (push-pull design structure). At power on, P3 is configured as an input
P4	9	I/O	P-port input-output (push-pull design structure). At power on, P4 is configured as an input
P5	10	I/O	P-port input-output (push-pull design structure). At power on, P5 is configured as an input
P6	11	I/O	P-port input-output (push-pull design structure). At power on, P6 is configured as an input
P7	12	I/O	P-port input-output (push-pull design structure). At power on, P7 is configured as an input
RESET	3	I	Active-low reset input. Connect to V <sub>CCI</sub> through a pull-up resistor, if no active connection is used
SCL	14	I	Serial clock bus. Connect to V <sub>CCI</sub> through a pull-up resistor
SDA	15	I/O	Serial data bus. Connect to V <sub>CCI</sub> through a pull-up resistor
V <sub>CCI</sub>	1	—	Supply voltage of I <sup>2</sup> C bus. Connect directly to the V <sub>CC</sub> of the external I <sup>2</sup> C master. Provides voltage level translation
V <sub>CCP</sub>	16	—	Supply voltage of TCA6408A-Q1 for P-ports

## 6 Specifications

### 6.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted) (see <sup>(1)</sup>)

				MIN	MAX	UNIT
$V_{CCI}$	Supply voltage for I <sup>2</sup> C pins			-0.5	3.6	V
$V_{CCP}$	Supply voltage for P-ports			-0.5	3.6	V
$V_I$	Input voltage <sup>(2)</sup>			-0.5	3.6	V
$V_O$	Output voltage <sup>(2)</sup>			-0.5	3.6	V
$I_{IK}$	Input clamp current	ADDR, $\overline{RESET}$ , SCL	$V_I < 0$		±20	mA
$I_{OK}$	Output clamp current	$\overline{INT}$	$V_O < 0$		±20	mA
$I_{IOK}$	Input/output clamp current	P-port	$V_O < 0$ or $V_O > V_{CCP}$		±20	mA
		SDA	$V_O < 0$ or $V_O > V_{CCI}$		±20	
$I_{OL}$	Continuous output low current	P-port	$V_O = 0$ to $V_{CCP}$		50	mA
	Continuous output low current	SDA, $\overline{INT}$	$V_O = 0$ to $V_{CCI}$		25	
$I_{OH}$	Continuous output high current	P-port	$V_O = 0$ to $V_{CCP}$		50	mA
$I_{CC}$	Continuous current through GND				200	mA
	Continuous current through $V_{CCP}$				160	
	Continuous current through $V_{CCI}$				10	
$T_{j(MAX)}$	Maximum junction temperature				135	°C
$T_{stg}$	Storage temperature			-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V
		Charged-device model (CDM), per AEC Q100-011	±1000	

- (1) AEC Q100-002 indicates HBM stressing is done in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
$V_{CCI}$ <sup>(1)</sup>	Supply voltage for I <sup>2</sup> C pins	SCL, SDA, $\overline{INT}$		1.65	3.6	V
$V_{CCP}$	Supply voltage for P-ports	P-ports, ADDR, $\overline{RESET}$		1.65	3.6	V
$V_{IH}$	High-level input voltage	SCL, SDA		$0.7 \times V_{CCI}$	$V_{CCI}$	V
		$\overline{RESET}$		$0.7 \times V_{CCI}$	3.6	
		ADDR, P7-P0		$0.7 \times V_{CCP}$	3.6	
$V_{IL}$	Low-level input voltage	SCL, SDA, $\overline{RESET}$		-0.5	$0.3 \times V_{CCI}$	V
		ADDR, P7-P0		-0.5	$0.3 \times V_{CCP}$	
$I_{OH}$	High-level output current	P00-P07			10	mA

- (1) For voltages applied above  $V_{CCI}$ , and increase in  $I_{CC}$  will result.

## Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$I_{OL}^{(2)}$	Low-level output current	P00-P07	$T_j = 65^\circ\text{C}$	25	mA
			$T_j = 85^\circ\text{C}$	18	
			$T_j = 105^\circ\text{C}$	9	
			$T_j = 125^\circ\text{C}$	4.5	
	$\overline{\text{INT}}$ , SDA		$T_j = 135^\circ\text{C}$	3.5	
			$T_j = 85^\circ\text{C}$	6	
			$T_j = 105^\circ\text{C}$	3	
			$T_j = 125^\circ\text{C}$	1.8	
		$T_j = 135^\circ\text{C}$	1.5		
$T_A$	Operating free-air temperature		-40	125	$^\circ\text{C}$

(2) The values shown apply to specific junction temperature. See the [Calculating Junction Temperature and Power Dissipation](#) section on how to calculate the junction temperature.

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TCA6408A-Q1	UNIT
		PW (TSSOP)	
		16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	122	$^\circ\text{C}/\text{W}$
$R_{\theta JC(\text{top})}$	Junction-to-case (top) thermal resistance	56.4	$^\circ\text{C}/\text{W}$
$R_{\theta JB}$	Junction-to-board thermal resistance	67.1	$^\circ\text{C}/\text{W}$
$\Psi_{JT}$	Junction-to-top characterization parameter	10.8	$^\circ\text{C}/\text{W}$
$\Psi_{JB}$	Junction-to-board characterization parameter	66.5	$^\circ\text{C}/\text{W}$

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range,  $V_{CCI} = 1.65\text{ V}$  to  $3.6\text{ V}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CCP}$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{IK}$	Input diode clamp voltage	$I_I = -18\text{ mA}$	1.65 V to 3.6 V	-1.2		V
$V_{PORR}$	Power-on reset voltage, $V_{CCP}$ rising <sup>(2)</sup>	$V_I = V_{CCP}$ or GND, $I_O = 0$	1.65 V to 3.6 V	1.2	1.5	V
$V_{PORF}$	Power-on reset voltage, $V_{CCP}$ falling <sup>(2)</sup>	$V_I = V_{CCP}$ or GND, $I_O = 0$	1.65 V to 3.6 V	0.6	1	V
$V_{OH}$	P-port high-level output voltage	$I_{OH} = -8\text{ mA}$	1.65 V	1.2	V	
			2.3 V	1.8		
			3 V	2.6		
			3.6 V	3.3		
	$I_{OH} = -10\text{ mA}$	1.65 V	1.0			
		2.3 V	1.7			
		3 V	2.5			
		3.6 V	3.2			

(1) All typical values are at nominal supply voltage (1.8-V, 2.5-V, or 3.3-V  $V_{CC}$ ) and  $T_A = 25^\circ\text{C}$ .

(2) When power (from 0 V) is applied to  $V_{CCP}$ , an internal power-on reset holds the TCA6408A-Q1 in a reset condition until  $V_{CCP}$  has reached  $V_{PORR}$ . At that time, the reset condition is released, and the TCA6408A-Q1 registers and I<sup>2</sup>C/SMBus state machine initialize to their default states. After that,  $V_{CCP}$  must be lowered to below  $V_{PORF}$  and back up to the operating voltage for a power-reset cycle.

## Electrical Characteristics (continued)

 over recommended operating free-air temperature range,  $V_{CCI} = 1.65\text{ V to }3.6\text{ V}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$V_{CCP}$	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
$V_{OL}$	P-port low-level output voltage	$I_{OL} = 8\text{ mA}$	1.65 V			0.45	V	
			2.3 V			0.25		
			3 V			0.25		
			3.6 V			0.23		
		$I_{OL} = 10\text{ mA}$	1.65 V			0.6		
			2.3 V			0.3		
			3 V			0.25		
			3.6 V			0.23		
$I_{OL}$	SDA	$V_{OL} = 0.4\text{ V}$	1.65 V to 3.6 V	3			mA	
	$\overline{\text{INT}}$			3	15			
$I_I$	SCL, SDA, $\overline{\text{RESET}}$	$V_I = V_{CCI}$ or GND	1.65 V to 3.6 V			$\pm 0.1$	$\mu\text{A}$	
	ADDR	$V_I = V_{CCP}$ or GND				$\pm 0.1$		
$I_{IH}$	P-port	$V_I = V_{CCP}$	1.65 V to 3.6 V			1	$\mu\text{A}$	
$I_{IL}$	P-port	$V_I = \text{GND}$	1.65 V to 3.6 V			1	$\mu\text{A}$	
$I_{CC}$ ( $I_{CCI} + I_{CCP}$ )	Operating mode	SDA, P-port, ADDR, $\overline{\text{RESET}}$	$V_I = V_{CC}$ or GND, I/O = inputs, $f_{SCL} = 400\text{ kHz}$ , No load	2.3 V to 3.6 V		9	36	$\mu\text{A}$
				1.65 V to 2.3 V		5	33	
	Standby mode	SCL, SDA, P-port, ADDR, $\overline{\text{RESET}}$	$V_I = V_{CC}$ or GND, I/O = inputs, $f_{SCL} = 0\text{ kHz}$ , No load	2.3 V to 3.6 V		1.2	10	
				1.65 V to 2.3 V		0.6	7	
$\Delta I_{CCI}$	Additional current in standby mode	SCL, SDA	1.65 V to 3.6 V			6	10	$\mu\text{A}$
		$\overline{\text{RESET}}$				$\overline{\text{RESET}}$ at $V_{CCI} - 0.6\text{ V}$ , Other inputs at $V_{CCI}$ or GND	6	
$\Delta I_{CCP}$		P-port, ADDR	1.65 V to 3.6 V			6	80	$\mu\text{A}$
$C_i$	SCL	$V_I = V_{CCI}$ or GND	1.65 V to 3.6 V			7	9	pF
$C_{io}$	SDA	$V_{IO} = V_{CCI}$ or GND	1.65 V to 3.6 V			8	10.5	pF
	P-port	$V_{IO} = V_{CCP}$ or GND				7	8	

## 6.6 I<sup>2</sup>C Interface Timing Requirements

 over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 17](#))

		MIN	MAX	UNIT
<b>I<sup>2</sup>C BUS—STANDARD MODE</b>				
$f_{scl}$	I <sup>2</sup> C clock frequency	0	100	kHz
$t_{sch}$	I <sup>2</sup> C clock high time	4		$\mu\text{s}$
$t_{scl}$	I <sup>2</sup> C clock low time	4.7		$\mu\text{s}$
$t_{sp}$	I <sup>2</sup> C spike time	0	50	ns
$t_{sds}$	I <sup>2</sup> C serial data setup time	250		ns
$t_{sdh}$	I <sup>2</sup> C serial data hold time	0		ns
$t_{icr}$	I <sup>2</sup> C input rise time		1000	ns
$t_{icf}$	I <sup>2</sup> C input fall time		300	ns
$t_{ocf}$	I <sup>2</sup> C output fall time, 10-pF to 400-pF bus		300	ns
$t_{buf}$	I <sup>2</sup> C bus free time between Stop and Start	4.7		$\mu\text{s}$
$t_{sts}$	I <sup>2</sup> C Start or repeater Start condition setup time	4.7		$\mu\text{s}$
$t_{sth}$	I <sup>2</sup> C Start or repeater Start condition hold time	4		$\mu\text{s}$
$t_{sps}$	I <sup>2</sup> C Stop condition setup time	4		$\mu\text{s}$

## I<sup>2</sup>C Interface Timing Requirements (continued)

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 17](#))

		MIN	MAX	UNIT
$t_{vd(data)}$	Valid data time, SCL low to SDA output valid		1	$\mu$ s
$t_{vd(ack)}$	Valid data time of ACK condition, ACK signal from SCL low to SDA (out) low		1	$\mu$ s
<b>I<sup>2</sup>C BUS—FAST MODE</b>				
$f_{scl}$	I <sup>2</sup> C clock frequency	0	400	kHz
$t_{sch}$	I <sup>2</sup> C clock high time	0.6		$\mu$ s
$t_{scl}$	I <sup>2</sup> C clock low time	1.3		$\mu$ s
$t_{sp}$	I <sup>2</sup> C spike time	0	50	ns
$t_{sds}$	I <sup>2</sup> C serial data setup time	100		ns
$t_{sdh}$	I <sup>2</sup> C serial data hold time	0		ns
$t_{icr}$	I <sup>2</sup> C input rise time	20	300	ns
$t_{icf}$	I <sup>2</sup> C input fall time	$20 \times (V_{cc}/5.5 \text{ V})$	300	ns
$t_{ocf}$	I <sup>2</sup> C output fall time, 10-pF to 400-pF bus	$20 \times (V_{cc}/5.5 \text{ V})$	300	ns
$t_{buf}$	I <sup>2</sup> C bus free time between Stop and Start	1.3		$\mu$ s
$t_{sts}$	I <sup>2</sup> C Start or repeater Start condition setup time	0.6		$\mu$ s
$t_{sth}$	I <sup>2</sup> C Start or repeater Start condition hold time	0.6		$\mu$ s
$t_{sps}$	I <sup>2</sup> C Stop condition setup time	0.6		$\mu$ s
$t_{vd(data)}$	Valid data time, SCL low to SDA output valid		1	$\mu$ s
$t_{vd(ack)}$	Valid data time of ACK condition, ACK signal from SCL low to SDA (out) low		1	$\mu$ s

## 6.7 Reset Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 20](#))

		MIN	MAX	UNIT
<b>I<sup>2</sup>C BUS—STANDARD and FAST MODE</b>				
$t_W$	Reset pulse duration	40		ns
$t_{REC}$	Reset recovery time	0		ns
$t_{RESET}$	Time to reset	600		ns

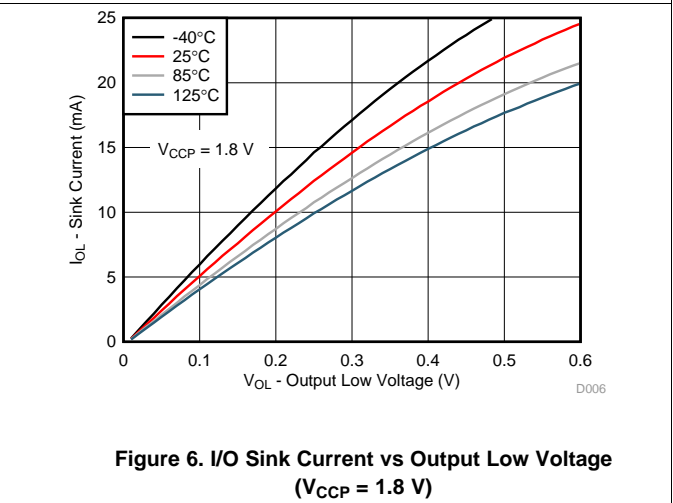
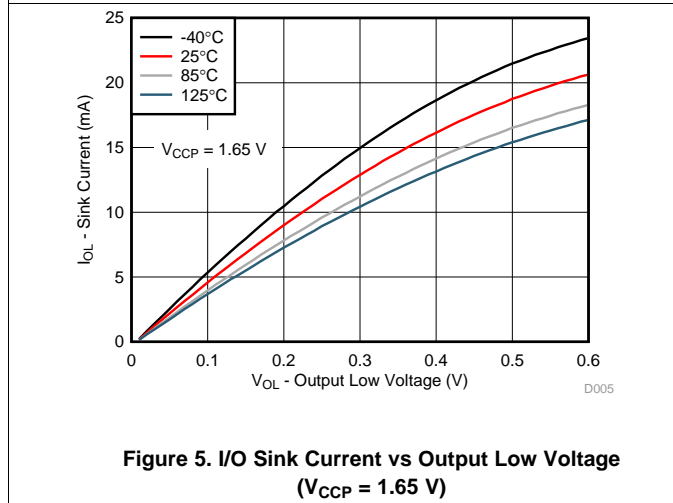
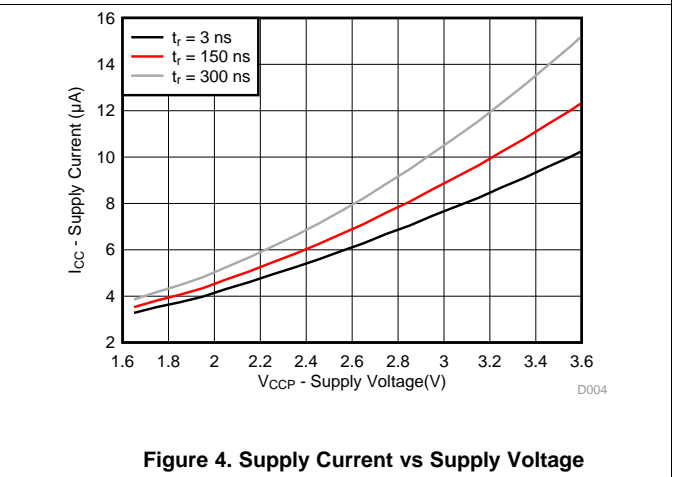
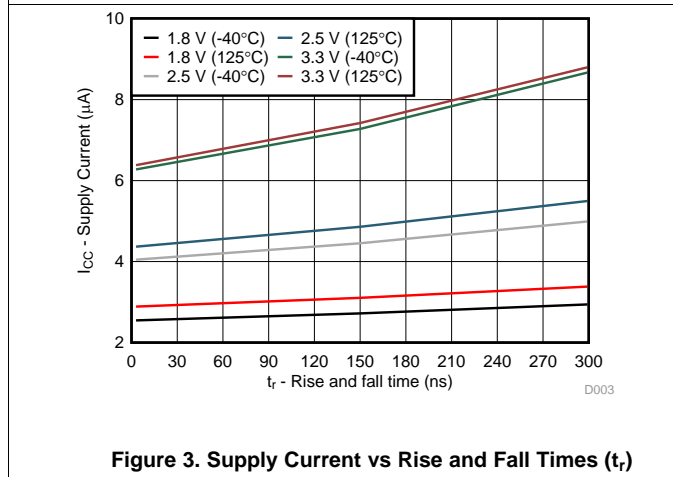
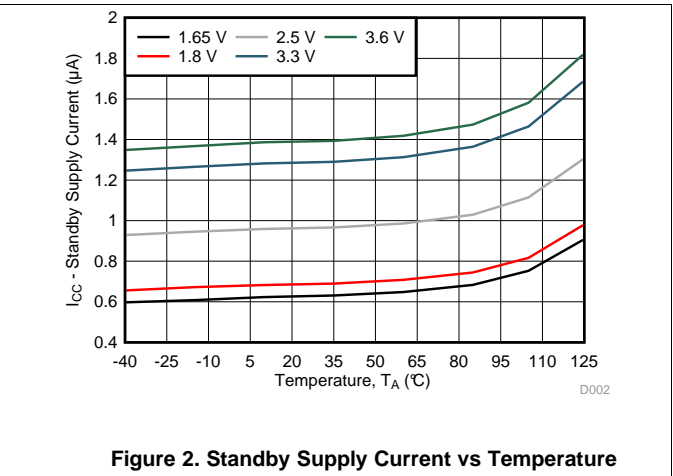
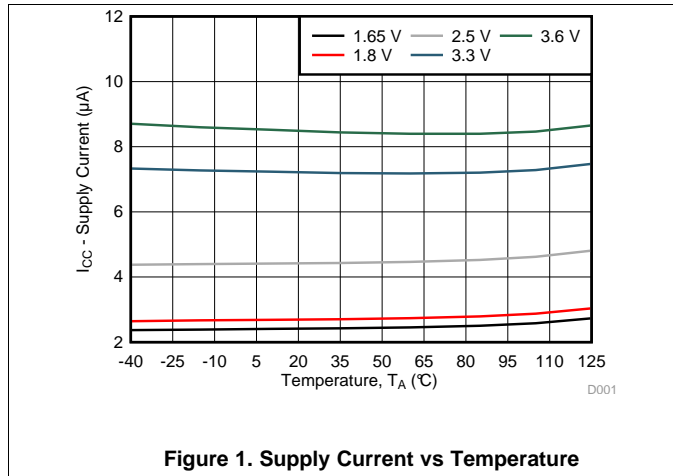
## 6.8 Switching Characteristics

over recommended operating free-air temperature range,  $C_L \leq 100$  pF (unless otherwise noted) (see [Figure 17](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
<b>I<sup>2</sup>C BUS—STANDARD and FAST MODE</b>					
$t_{iv}$	Interrupt valid time	P-Port		4	$\mu$ s
$t_{ir}$	Interrupt reset delay time	SCL		4	$\mu$ s
$t_{pv}$	Output data valid	SCL		400	ns
$t_{ps}$	Input data setup time	P-Port	0		ns
$t_{ph}$	Input data hold time	P-Port	300		ns

### 6.9 Typical Characteristics

T<sub>A</sub> = 25°C (unless otherwise noted)





Typical Characteristics (continued)

T<sub>A</sub> = 25°C (unless otherwise noted)

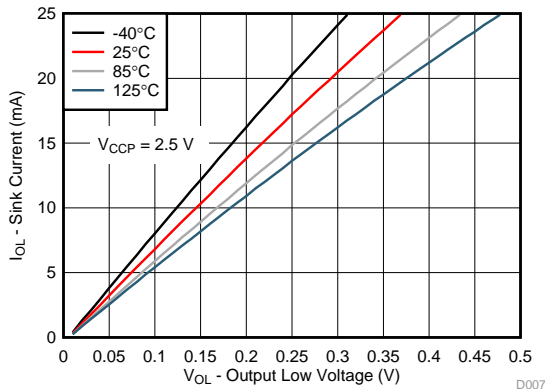


Figure 7. I/O Sink Current vs Output Low Voltage (V<sub>C<sub>CP</sub></sub> = 2.5 V)

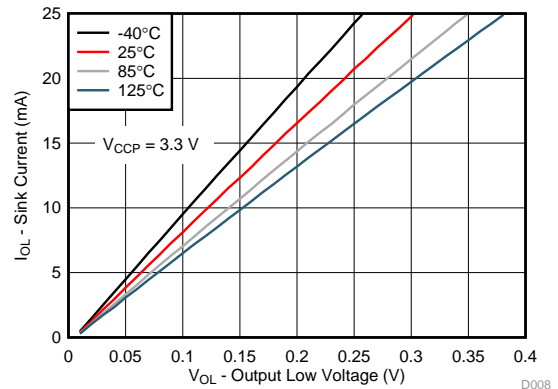


Figure 8. I/O Sink Current vs Output Low Voltage (V<sub>C<sub>CP</sub></sub> = 3.3 V)

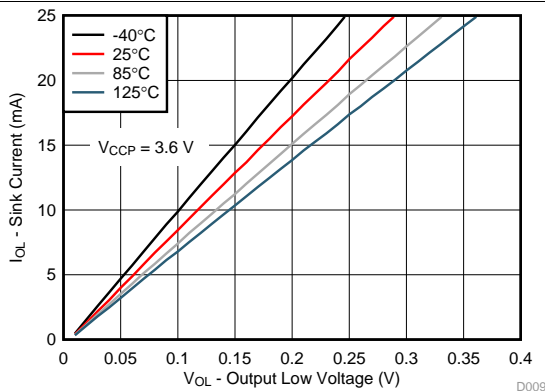


Figure 9. I/O Sink Current vs Temperature (V<sub>C<sub>CP</sub></sub> = 3.6 V)

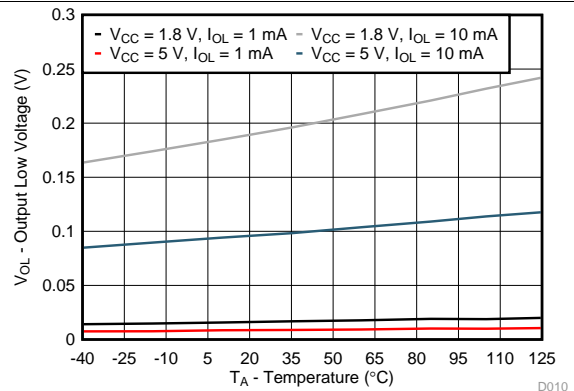


Figure 10. I/O Low Voltage vs Temperature

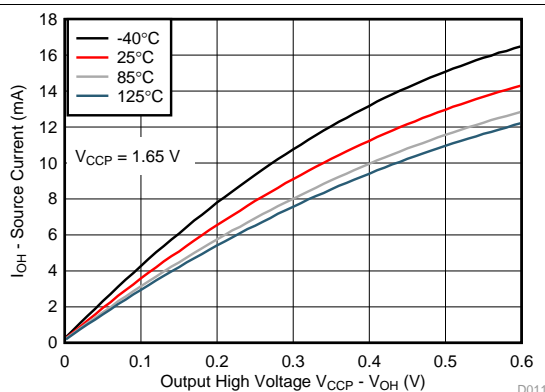


Figure 11. I/O Source Current vs Output High Voltage (V<sub>C<sub>CP</sub></sub> = 1.65 V)

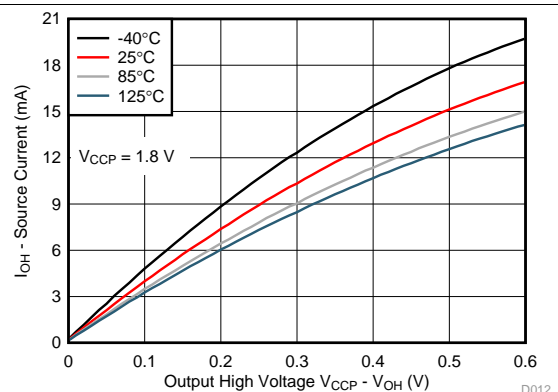


Figure 12. I/O Source Current vs Output High Voltage (V<sub>C<sub>CP</sub></sub> = 1.8 V)

Typical Characteristics (continued)

T<sub>A</sub> = 25°C (unless otherwise noted)

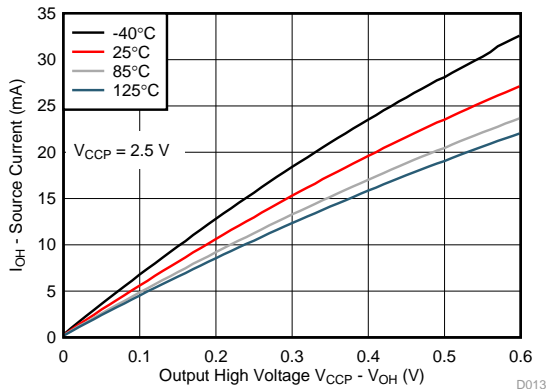


Figure 13. I/O Source Current vs Output High Voltage (V<sub>CCP</sub> = 2.5 V)

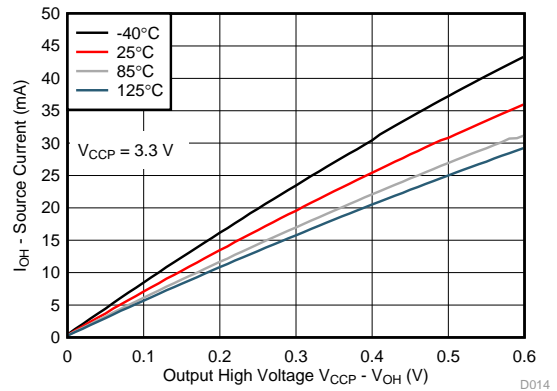


Figure 14. I/O Source Current vs Output High Voltage (V<sub>CCP</sub> = 3.3 V)

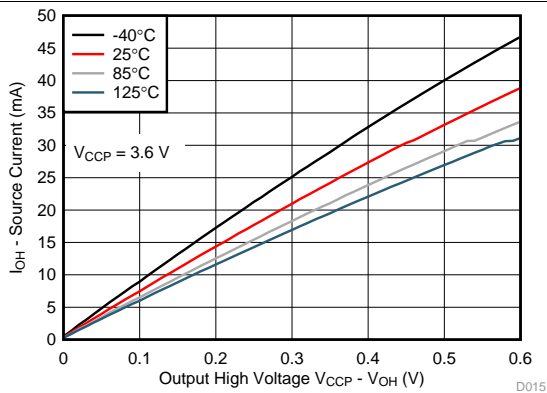


Figure 15. I/O Source Current vs Output High Voltage (V<sub>CCP</sub> = 3.6 V)

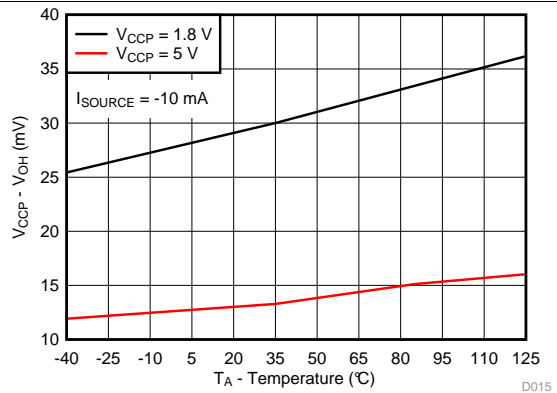
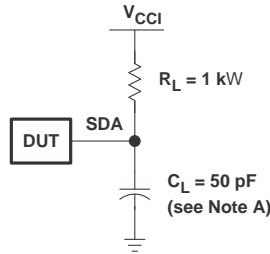
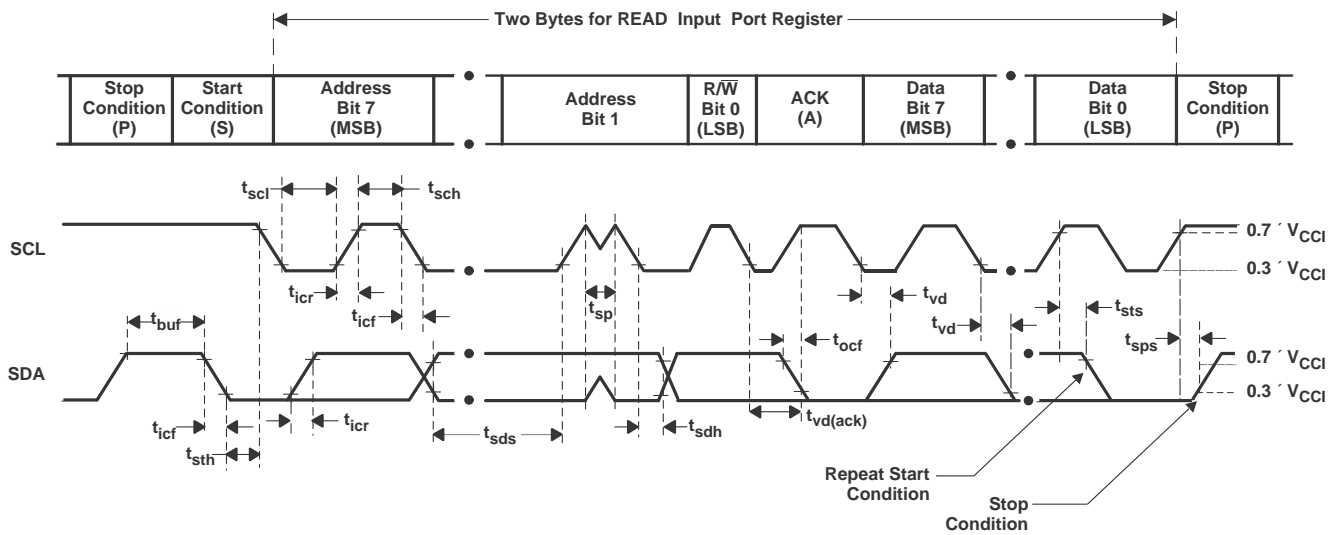


Figure 16. I/O High Voltage vs Temperature

7 Parameter Measurement Information



SDA LOAD CONFIGURATION



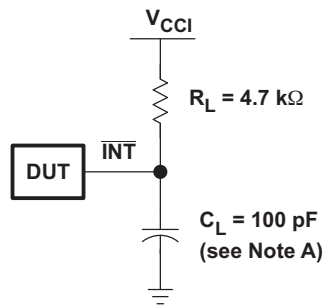
VOLTAGE WAVEFORMS

BYTE	DESCRIPTION
1	I <sup>2</sup> C address
2	Input register port data

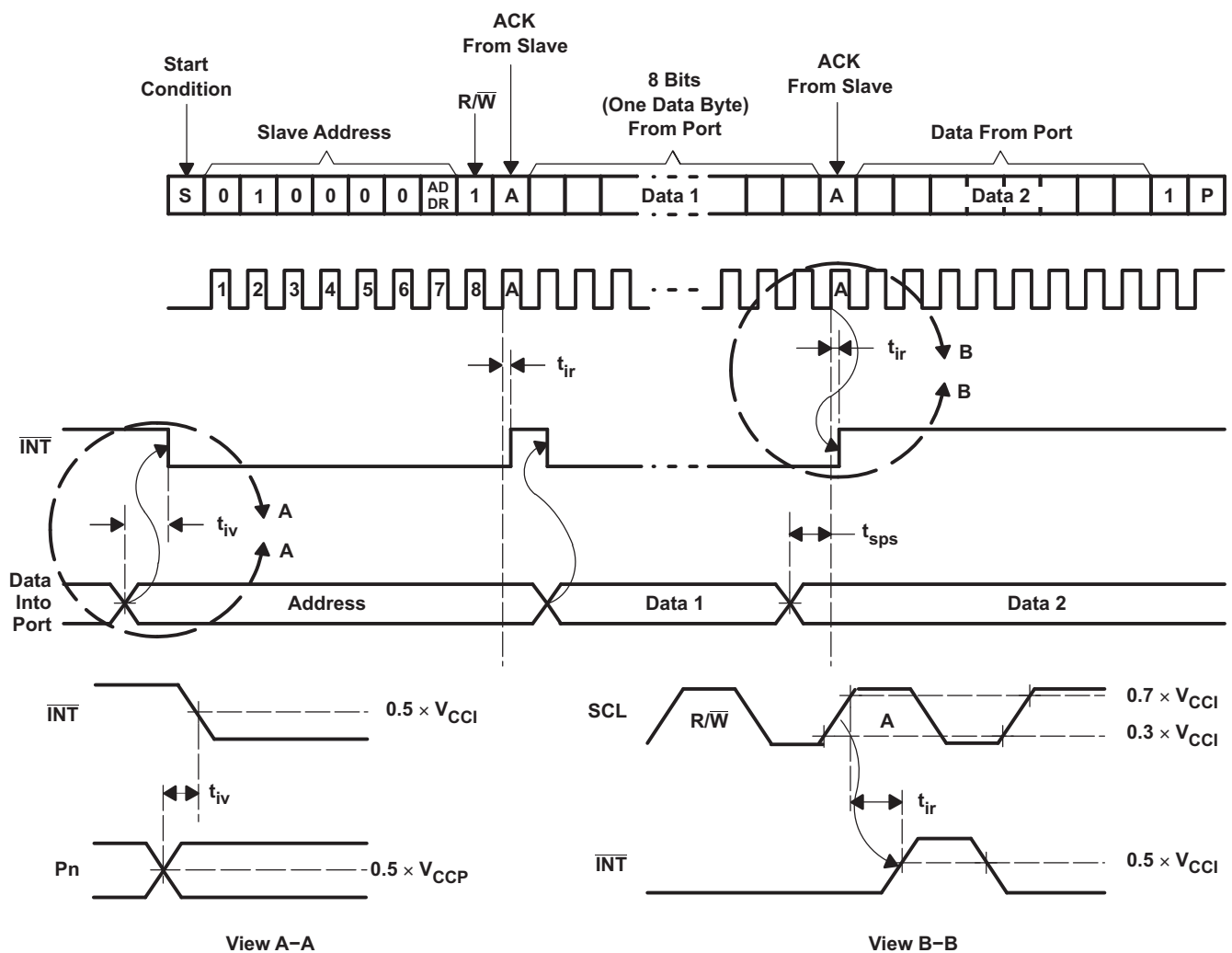
- A.  $C_L$  includes probe and jig capacitance.  $t_{ocf}$  is measured with  $C_L$  of 10 pF or 400 pF.
- B. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_r/t_f \leq 30$  ns.

Figure 17. I<sup>2</sup>C Interface Load Circuit and Voltage Waveforms

Parameter Measurement Information (continued)



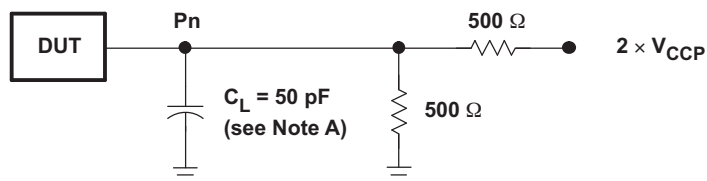
INTERRUPT LOAD CONFIGURATION



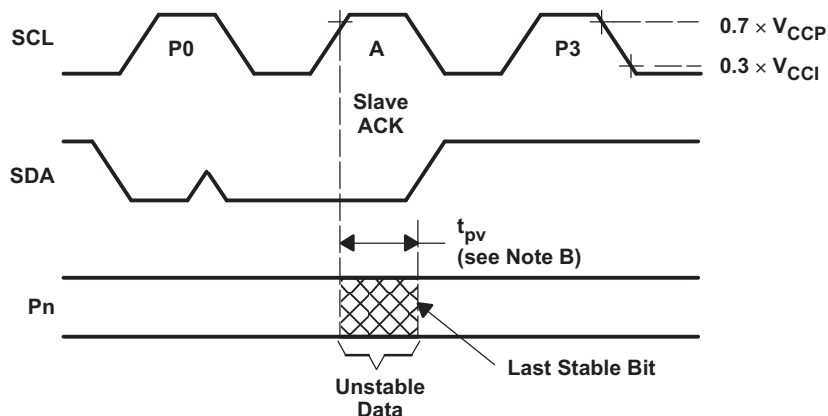
- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r/t_f \leq 30$  ns.

Figure 18. Interrupt Load Circuit and Voltage Waveforms

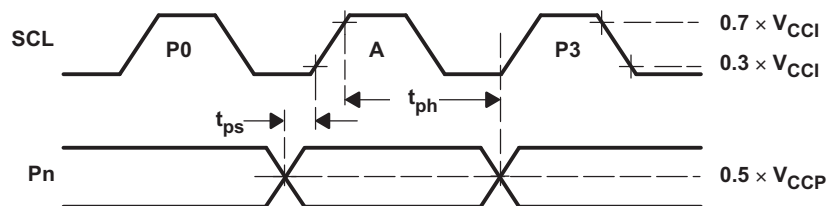
Parameter Measurement Information (continued)



P-PORT LOAD CONFIGURATION



WRITE MODE (R/W = 0)

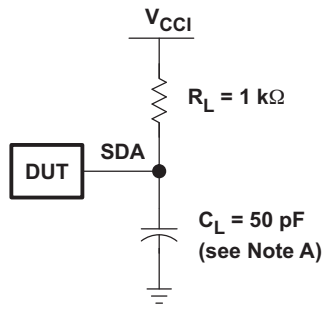


READ MODE (R/W = 1)

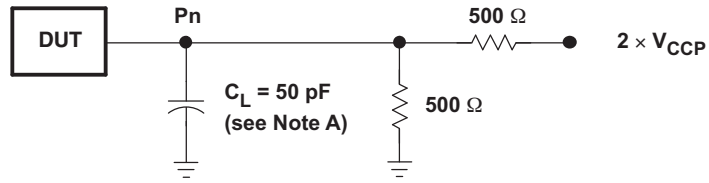
- A. C<sub>L</sub> includes probe and jig capacitance.
- B. t<sub>pv</sub> is measured from 0.7 × V<sub>CC</sub> on SCL to 50% I/O (Pn) output.
- C. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub>/t<sub>f</sub> ≤ 30 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 19. P-Port Load Circuit and Timing Waveforms

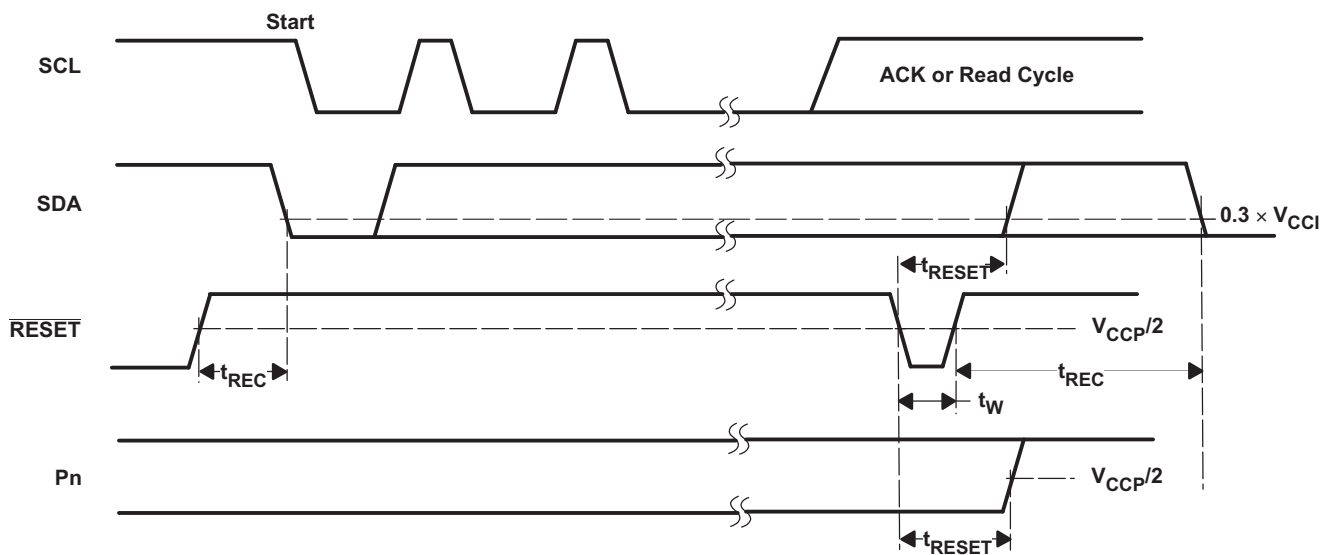
Parameter Measurement Information (continued)



SDA LOAD CONFIGURATION



P-PORT LOAD CONFIGURATION



- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r/t_f \leq 30\text{ ns}$ .
- C. The outputs are measured one at a time, with one transition per measurement.
- D. I/Os are configured as inputs.

Figure 20. Reset Load Circuits and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

The bidirectional voltage-level translation in the TCA6408A-Q1 is provided through  $V_{CCI}$ .  $V_{CCI}$  must be connected to the  $V_{CC}$  of the external SCL/SDA lines. This indicates the  $V_{CC}$  level of the I<sup>2</sup>C bus to the TCA6408A-Q1. The voltage level on the P-port of the TCA6408A-Q1 is determined by  $V_{CCP}$ .

The TCA6408A-Q1 consists of one 8-bit Configuration (input or output selection), Input, Output, and Polarity Inversion (active high) Register. At power on, the I/Os are configured as inputs. However, the system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input or Output Register. The polarity of the Input Port Register can be inverted with the Polarity Inversion Register. All registers can be read by the system master.

The system master can reset the TCA6408A-Q1 in the event of a timeout or other improper operation by asserting a low in the  $\overline{\text{RESET}}$  input. The power-on reset puts the registers in their default state and initializes the I<sup>2</sup>C/SMBus state machine. The  $\overline{\text{RESET}}$  pin causes the same reset/initialization to occur without depowering the part.

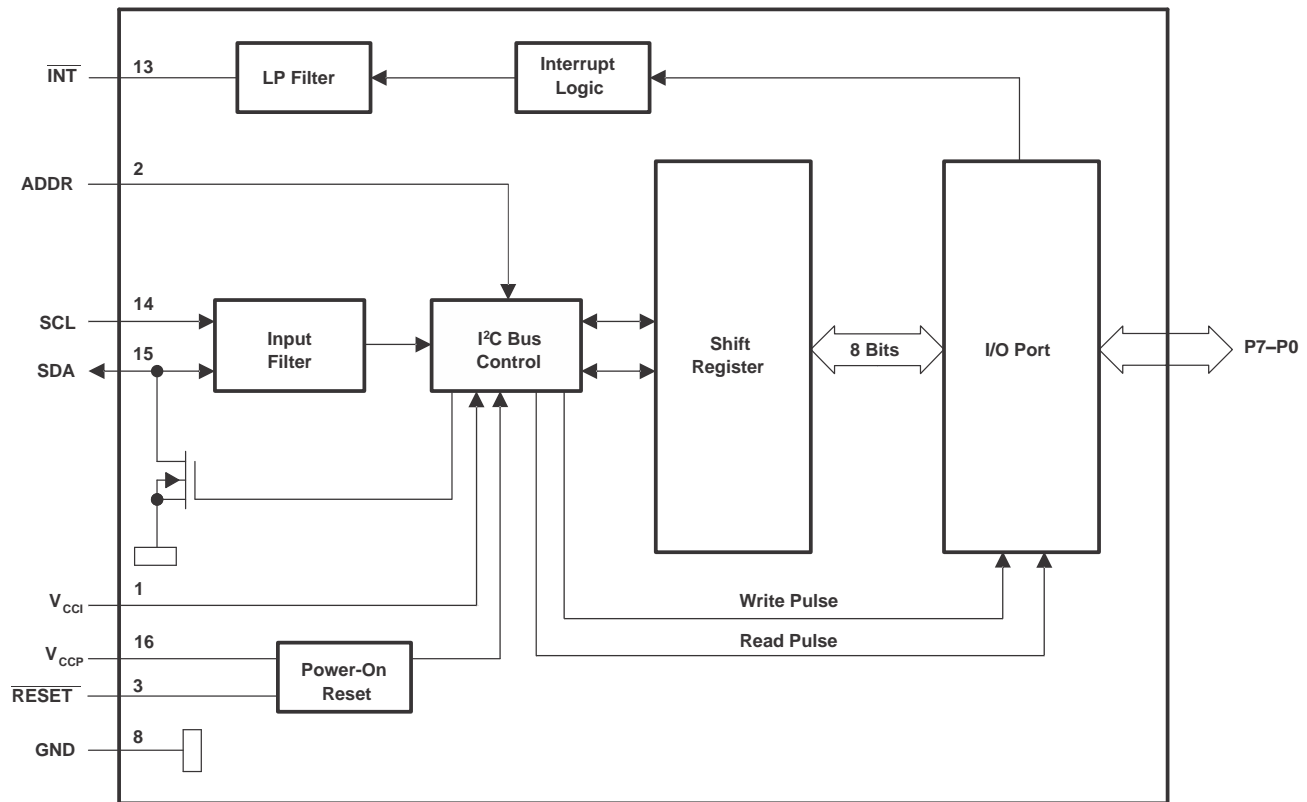
The TCA6408A-Q1 open-drain interrupt ( $\overline{\text{INT}}$ ) output is activated when any input state differs from its corresponding Input Port Register state and is used to indicate to the system master that an input state has changed.

$\overline{\text{INT}}$  can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I<sup>2</sup>C bus. Thus, the TCA6408A-Q1 can remain a simple slave device.

The device P-port outputs have high-current sink capabilities for directly driving LEDs while consuming low device current.

One hardware pin (ADDR) can be used to program and vary the fixed I<sup>2</sup>C address and allow up to two devices to share the same I<sup>2</sup>C bus or SMBus.

## 8.2 Functional Block Diagrams



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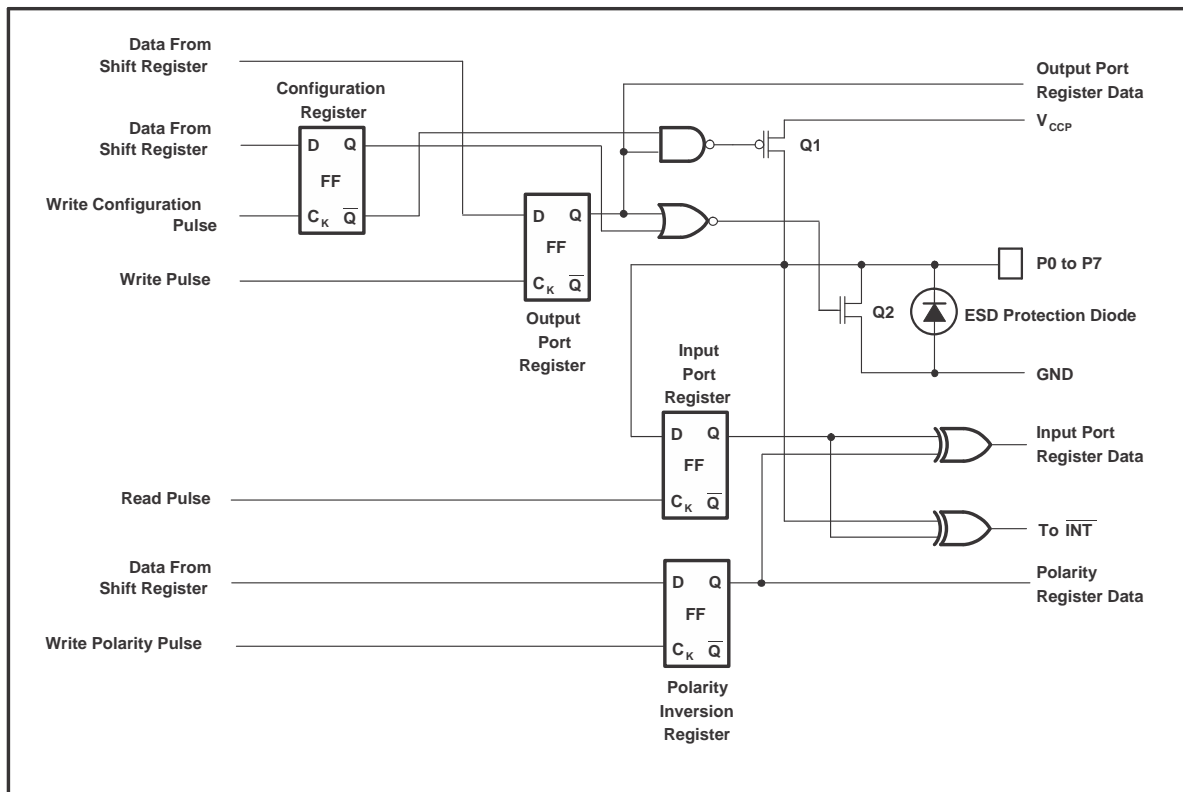
All pin numbers shown are for the PW package.

All I/Os are set to inputs at reset.

**Figure 21. Logic Diagram (Positive Logic)**



Functional Block Diagrams (continued)



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On power up or reset, all registers return to default values.

Figure 22. Simplified Schematic of P0 to P7

## 8.3 Feature Description

### 8.3.1 Voltage Translation

Table 1 shows some common supply voltage options for voltage translation between the I<sup>2</sup>C bus and the P-ports of the TCA6408A-Q1.

**Table 1. Voltage Translation**

V <sub>CCI</sub> (SCL AND SDA OF I <sup>2</sup> C MASTER) (V)	V <sub>CCP</sub> (P-PORT) (V)
1.8	1.8
1.8	2.5
1.8	3.3
2.5	1.8
2.5	2.5
2.5	3.3
3.3	1.8
3.3	2.5
3.3	3.3

### 8.3.2 I/O Port

When an I/O is configured as an input, FETs Q1 and Q2 are off, which creates a high-impedance input. The input voltage may be raised above V<sub>CC</sub> to a maximum of 3.6 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the output port register. In this case, there are low-impedance paths between the I/O pin and either V<sub>CC</sub> or GND. The external voltage applied to this I/O pin must not exceed the recommended levels for proper operation.

### 8.3.3 Interrupt Output ( $\overline{\text{INT}}$ )

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time t<sub>IV</sub>, the signal  $\overline{\text{INT}}$  is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting or when data is read from the port that generated the interrupt. Resetting occurs in the read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as  $\overline{\text{INT}}$ .

Reading from or writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register.

The  $\overline{\text{INT}}$  output has an open-drain structure and requires pull-up resistor to V<sub>CCP</sub> or V<sub>CCI</sub>, depending on the application.  $\overline{\text{INT}}$  must be connected to the voltage source of the device that requires the interrupt information.

### 8.3.4 Reset Input ( $\overline{\text{RESET}}$ )

The  $\overline{\text{RESET}}$  input can be asserted to initialize the system while keeping the V<sub>CCP</sub> at its operating level. A reset can be accomplished by holding the  $\overline{\text{RESET}}$  pin low for a minimum of t<sub>w</sub>. The TCA6408A-Q1 registers and I<sup>2</sup>C/SMBus state machine are changed to their default state when  $\overline{\text{RESET}}$  is low (0). When  $\overline{\text{RESET}}$  is high (1), the I/O levels at the P-port can be changed externally or through the master. This input requires a pull-up resistor to V<sub>CCI</sub>, if no active connection is used. It is not recommended to assert the  $\overline{\text{RESET}}$  pin during communication with the TCA6408A-Q1. Assertion of  $\overline{\text{RESET}}$  during communication can result in data corruption.

## 8.4 Device Functional Modes

### 8.4.1 Power-On Reset (POR)

When power (from 0 V) is applied to  $V_{CCP}$ , an internal power-on reset holds the TCA6408A-Q1 in a reset condition until  $V_{CCP}$  has reached  $V_{PORR}$ . At that time, the reset condition is released, and the TCA6408A-Q1 registers and I<sup>2</sup>C/SMBus state machine initialize to their default states. After that,  $V_{CCP}$  must be lowered to below  $V_{PORF}$  and back up to the operating voltage for a power-reset cycle.

### 8.4.2 Powered-Up

When power has been applied to both  $V_{CCP}$  and  $V_{CCI}$  and a POR has taken place, the device is in a functioning mode. The device is always ready to receive new requests via the I<sup>2</sup>C bus.

## 8.5 Programming

### 8.5.1 I<sup>2</sup>C Interface

The TCA6408A-Q1 has a standard bidirectional I<sup>2</sup>C interface that is controlled by a master device in order to be configured or read the status of this device. Each slave on the I<sup>2</sup>C bus has a specific device address to differentiate between other slave devices that are on the same I<sup>2</sup>C bus. Many slave devices require configuration upon startup to set the behavior of the device. This is typically done when the master accesses internal register maps of the slave, which have unique register addresses. A device can have one or multiple registers where data is stored, written, or read.

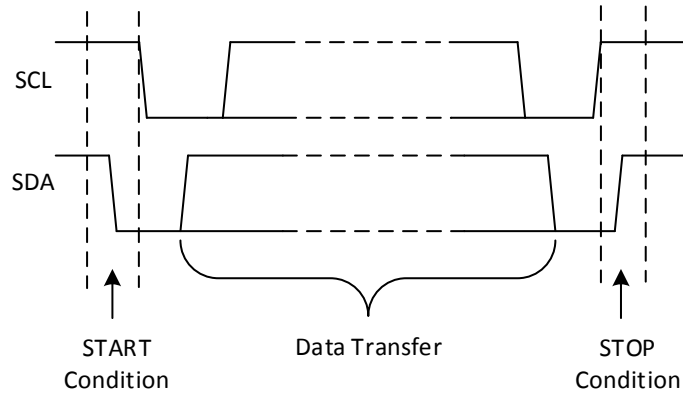
The physical I<sup>2</sup>C interface consists of the serial clock (SCL) and serial data (SDA) lines. Both SDA and SCL lines must be connected to  $V_{CC}$  through a pull-up resistor. The size of the pull-up resistor is determined by the amount of capacitance on the I<sup>2</sup>C lines. (For further details, see the application report, *I<sup>2</sup>C Pull-up Resistor Calculation (SLVA689)*). Data transfer may be initiated only when the bus is idle. A bus is considered idle if both SDA and SCL lines are high after a STOP condition. See [Figure 23](#) and [Figure 24](#).

The following is the general procedure for a master to access a slave device:

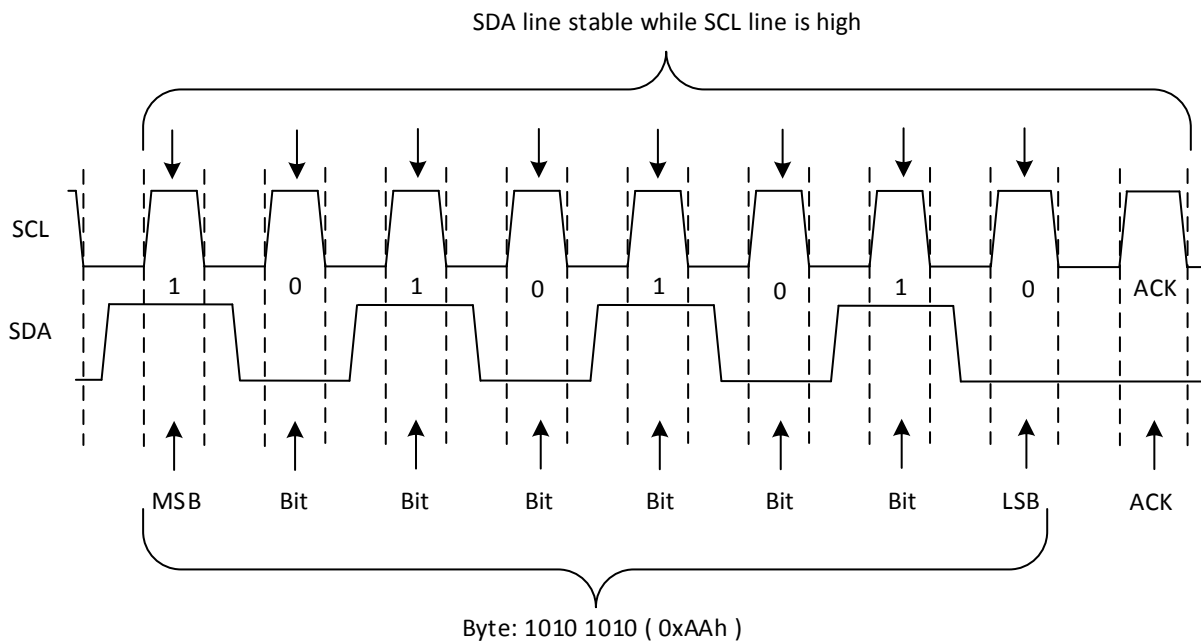
1. If a master wants to send data to a slave:
  - Master-transmitter sends a START condition and addresses the slave-receiver.
  - Master-transmitter sends data to slave-receiver.
  - Master-transmitter terminates the transfer with a STOP condition.
2. If a master wants to receive or read data from a slave:
  - Master-receiver sends a START condition and addresses the slave-transmitter.
  - Master-receiver sends the requested register to read to slave-transmitter.
  - Master-receiver receives data from the slave-transmitter.

## Programming (continued)

- Master-receiver terminates the transfer with a STOP condition.



**Figure 23. Definition of Start and Stop Conditions**



**Figure 24. Bit Transfer**

Table 2 shows the interface definition for the TCA6408A-Q1 device.

**Table 2. Interface Definition**

BYTE	BIT							
	7 (MSB)	6	5	4	3	2	1	0 (LSB)
I <sup>2</sup> C slave address	L	H	L	L	L	L	ADDR	R/W
I/O data bus	P7	P6	P5	P4	P3	P2	P1	P0

### 8.5.2 Bus Transactions

Data must be sent to and received from the slave devices, and this is accomplished by reading from or writing to registers in the slave device.

## Programming (continued)

Registers are locations in the memory of the slave which contain information, whether it be the configuration information or some sampled data to send back to the master. The master must write information to these registers in order to instruct the slave device to perform a task.

While it is common to have registers in I<sup>2</sup>C slaves, note that not all slave devices will have registers. Some devices are simple and contain only 1 register, which may be written to directly by sending the register data immediately after the slave address, instead of addressing a register. An example of a single-register device is an 8-bit I<sup>2</sup>C switch, which is controlled via I<sup>2</sup>C commands. Since it has 1 bit to enable or disable a channel, there is only 1 register needed, and the master merely writes the register data after the slave address, skipping the register number.

### 8.5.2.1 Writes

To write on the I<sup>2</sup>C bus, the master sends a START condition on the bus with the address of the slave, as well as the last bit (the R/W bit) set to 0, which signifies a write. After the slave sends the acknowledge bit, the master then sends the register address of the register to which it wishes to write. The slave will acknowledge again, letting the master know it is ready. After this, the master starts sending the register data to the slave until the master has sent all the data necessary (which is sometimes only a single byte), and the master terminates the transmission with a STOP condition.

Figure 25 and Figure 26 show an example of writing a single byte to a slave register.

- Master controls SDA line
- Slave controls SDA line

#### Write to one register in a device

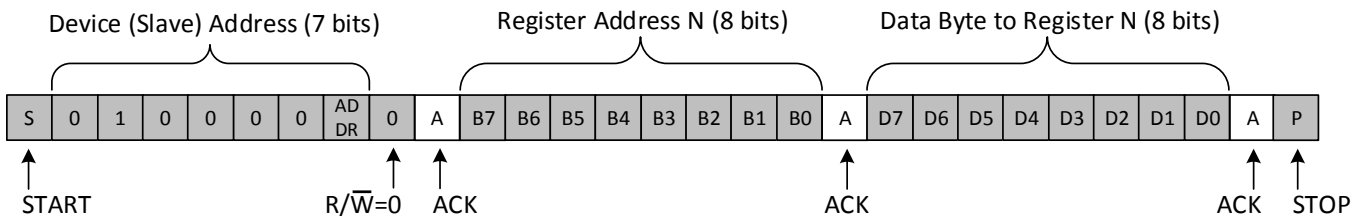


Figure 25. Write to Register

- Master controls SDA line
- Slave controls SDA line

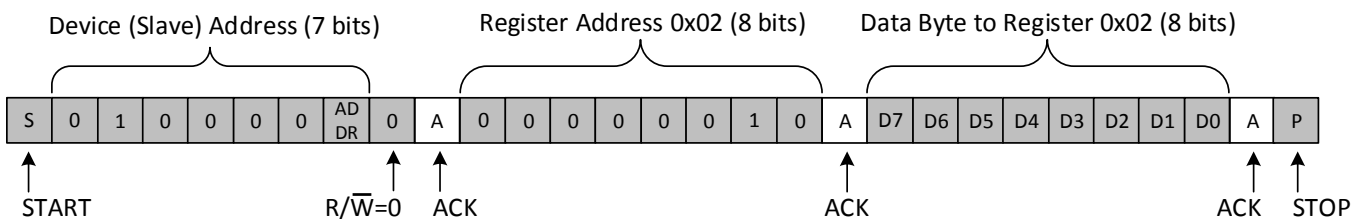


Figure 26. Write to the Polarity Inversion Register

## Programming (continued)

### 8.5.2.2 Reads

Reading from a slave is very similar to writing, but requires some additional steps. In order to read from a slave, the master must first instruct the slave which register it wishes to read from. This is done by the master starting off the transmission in a similar fashion as the write, by sending the address with the R/W bit equal to 0 (signifying a write), followed by the register address it wishes to read from. When the slave acknowledges this register address, the master sends a START condition again, followed by the slave address with the R/W bit set to 1 (signifying a read). This time, the slave acknowledges the read request, and the master releases the SDA bus but continues supplying the clock to the slave. During this part of the transaction, the master becomes the master-receiver, and the slave becomes the slave-transmitter.

The master continues to send out the clock pulses, but releases the SDA line so that the slave can transmit data. At the end of every byte of data, the master sends an ACK to the slave, letting the slave know that it is ready for more data. When the master has received the number of bytes it is expecting, it sends a NACK, signaling to the slave to halt communications and release the bus. The master follows this up with a STOP condition.

Read transactions that are performed without writing to the address of the device and simply supply the command byte will result in a NACK.

Figure 27 and Figure 28 show an example of reading a single byte from a slave register.

- Master controls SDA line
- Slave controls SDA line

#### Read from one register in a device

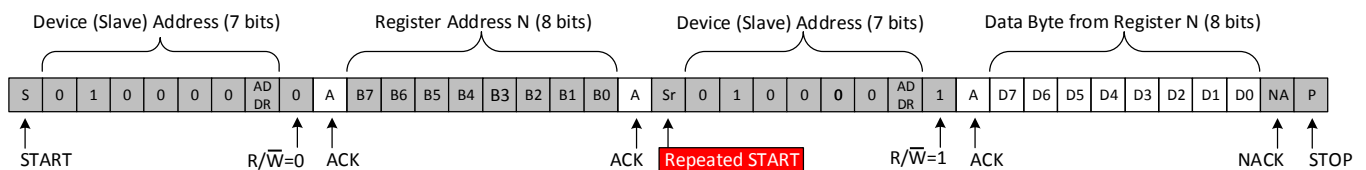
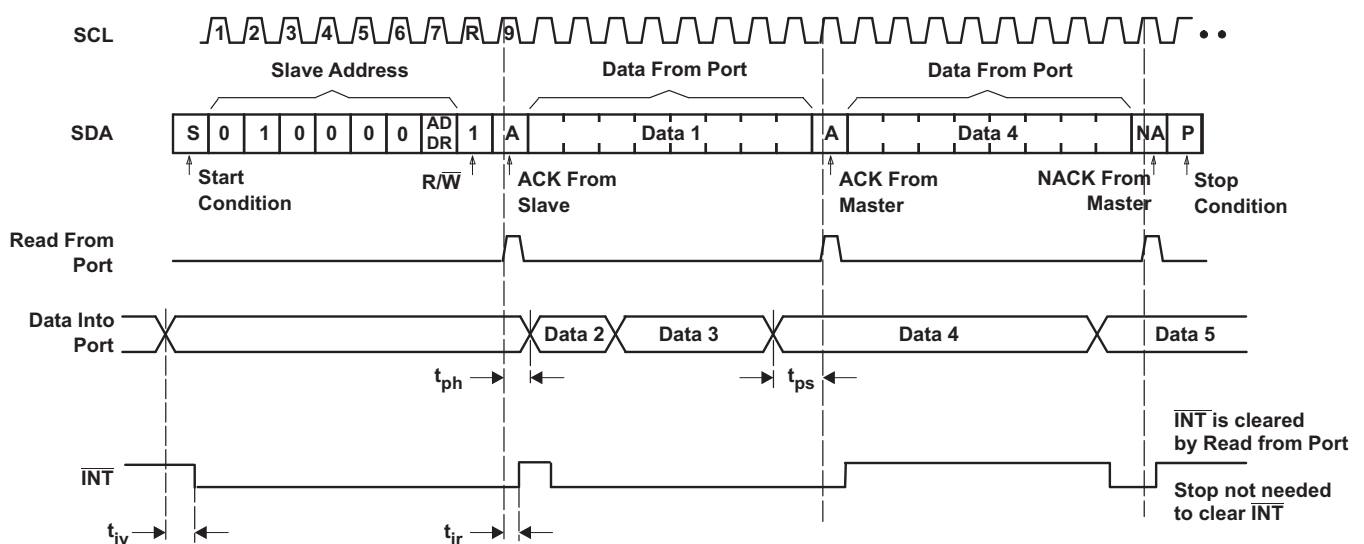


Figure 27. Read from Register



- A. Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port Register).
- B. This figure eliminates the command byte transfer, a restart, and slave address call between the initial slave address call and actual data transfer from P-port (see Figure 27).

Figure 28. Read from Input Port Register

## 8.6 Register Map

### 8.6.1 Device Address

The address of the TCA6408A-Q1 is shown in [Figure 29](#).

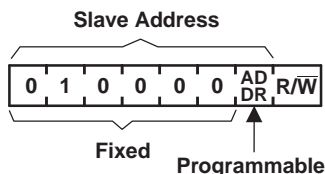


Figure 29. TCA6408A-Q1 Address

[Table 3](#) shows the TCA6408A-Q1 address reference.

Table 3. Address Reference

ADDR	I <sup>2</sup> C BUS SLAVE ADDRESS
L	32 (decimal), 20 (hexadecimal)
H	33 (decimal), 21 (hexadecimal)

The last bit of the slave address defines the operation (read or write) to be performed. A high (1) selects a read operation, while a low (0) selects a write operation.

### 8.6.2 Control Register and Command Byte

Following the successful acknowledgment of the address byte, the bus master sends a command byte (see [Table 4](#)), which is stored in the Control Register in the TCA6408A-Q1. Two bits of this data byte state both the operation (read or write) and the internal registers (Input, Output, Polarity Inversion, or Configuration) that is affected. This register can be written or read through the I<sup>2</sup>C bus. The command byte is sent only during a write transmission. See [Figure 30](#).

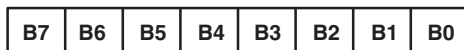


Figure 30. Control Register Bits

Table 4. Command Byte

CONTROL REGISTER BITS								COMMAND BYTE (HEX)	REGISTER	PROTOCOL	POWER-UP DEFAULT
B7	B6	B5	B4	B3	B2	B1	B0				
0	0	0	0	0	0	0	0	00	Input Port	Read byte	xxxx xxxx
0	0	0	0	0	0	0	1	01	Output Port	Read/write byte	1111 1111
0	0	0	0	0	0	1	0	02	Polarity Inversion	Read/write byte	0000 0000
0	0	0	0	0	0	1	1	03	Configuration	Read/write byte	1111 1111

### 8.6.3 Register Descriptions

The Input Port Register (register 0) reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration Register. They act only on read operation. Writes to this register have no effect. The default value (X) is determined by the externally applied logic level. Before a read operation, a write transmission is sent with the command byte to indicate to the I<sup>2</sup>C device that the Input Port Register will be accessed next. See [Table 5](#).

**Table 5. Register 0 (Input Port Register)**

BIT	I-7	I-6	I-5	I-4	I-3	I-2	I-1	I-0
DEFAULT	X	X	X	X	X	X	X	X

The Output Port Register (register 1) shows the outgoing logic levels of the pins defined as outputs by the Configuration Register. Bit values in this register have no effect on pins defined as inputs. In turn, reads from this register reflect the value that is in the flip-flop controlling the output selection, not the actual pin value. See [Table 6](#).

**Table 6. Register 1 (Output Port Register)**

BIT	O-7	O-6	O-5	O-4	O-3	O-2	O-1	O-0
DEFAULT	1	1	1	1	1	1	1	1

The Polarity Inversion Register (register 2) allows polarity inversion of pins defined as inputs by the Configuration Register. If a bit in this register is set (written with 1), the polarity of the corresponding port pin is inverted. If a bit in this register is cleared (written with a 0), the original polarity of the corresponding port pin is retained. See [Table 7](#).

**Table 7. Register 2 (Polarity Inversion Register)**

BIT	N-7	N-6	N-5	N-4	N-3	N-2	N-1	N-0
DEFAULT	0	0	0	0	0	0	0	0

The Configuration Register (register 3) configures the direction of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output. See [Table 8](#).

**Table 8. Register 3 (Configuration Register)**

BIT	C-7	C-6	C-5	C-4	C-3	C-2	C-1	C-0
DEFAULT	1	1	1	1	1	1	1	1



## 9 Application and Implementation

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### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

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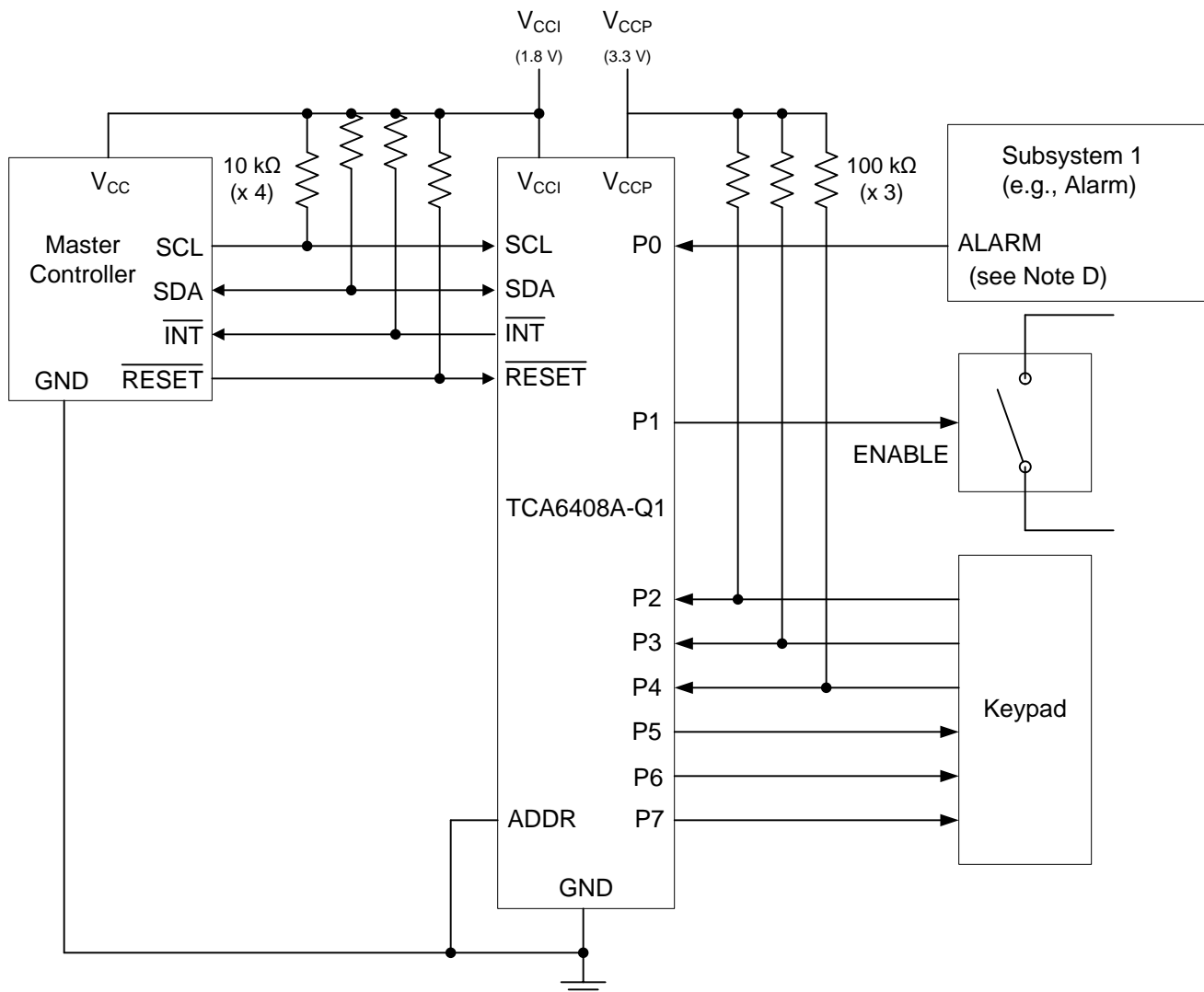
### 9.1 Application Information

Applications of the TCA6408A-Q1 has this device connected as a slave to an I<sup>2</sup>C master (processor), and the I<sup>2</sup>C bus may contain any number of other slave devices. The TCA6408A-Q1 is in a remote location from the master, placed close to the GPIOs to which the master needs to monitor or control.

A typical application of the TCA6408A-Q1 operates with a lower voltage on the master side ( $V_{CC1}$ ), and a higher voltage on the P-port side ( $V_{CCP}$ ). The P-ports can be configured as outputs connected to inputs of devices such as enable, reset, power select, the gate of a switch, and LEDs. The P-ports can also be configured as inputs to receive data from interrupts, alarms, status outputs, or push buttons.

## 9.2 Typical Application

Figure 31 shows an application in which the TCA6408A-Q1 can be used.



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- A. Device address configured as 0100000 for this example.
- B. P0 and P2–P4 are configured as inputs.
- C. P1 and P5–P7 are configured as outputs.
- D. Resistors are required for inputs (on P-port) that may float. If a driver to an input will never let the input float, a resistor is not needed. Outputs (in the P-port) do not need pull-up resistors.

**Figure 31. Typical Application Schematic**

### 9.2.1 Design Requirements

#### 9.2.1.1 Calculating Junction Temperature and Power Dissipation

When designing with the TCA6408A-Q1, it is important that the *Recommended Operating Conditions* not be violated. Many of the parameters of this device are rated based on junction temperature. So junction temperature must be calculated in order to verify that safe operation of the device is met. The basic equation for junction temperature is shown in Equation 1.

$$T_j = T_A + (\theta_{JA} \times P_d) \quad (1)$$

## Typical Application (continued)

$\theta_{JA}$  is the standard junction to ambient thermal resistance measurement of the package, as seen in [Thermal Information](#) table.  $P_d$  is the total power dissipation of the device, and the approximation is shown in [Equation 2](#).

$$P_d \approx (I_{CC\_STATIC} \times V_{CC}) + \sum P_{d\_PORT\_L} + \sum P_{d\_PORT\_H} \quad (2)$$

[Equation 2](#) is the approximation of power dissipation in the device. The equation is the static power plus the summation of power dissipated by each port (with a different equation based on if the port is outputting high, or outputting low. If the port is set as an input, then power dissipation is the input leakage of the pin multiplied by the voltage on the pin). Note that this ignores power dissipation in the  $\overline{INT}$  and SDA pins, assuming these transients to be small. They can easily be included in the power dissipation calculation by using [Equation 3](#) to calculate the power dissipation in  $\overline{INT}$  or SDA while they are pulling low, and this gives maximum power dissipation.

$$P_{d\_PORT\_L} = (I_{OL} \times V_{OL}) \quad (3)$$

[Equation 3](#) shows the power dissipation for a single port which is set to output low. The power dissipated by the port is the  $V_{OL}$  of the port multiplied by the current it is sinking.

$$P_{d\_PORT\_H} = (I_{OH} \times (V_{CC} - V_{OH})) \quad (4)$$

[Equation 4](#) shows the power dissipation for a single port which is set to output high. The power dissipated by the port is the current sourced by the port multiplied by the voltage drop across the device (difference between  $V_{CC}$  and the output voltage).

### 9.2.1.2 Minimizing $I_{CC}$ When I/O is Used to Control LEDs

When the I/Os are used to control LEDs, normally they are connected to  $V_{CC}$  through a resistor as shown in [Figure 31](#). The LED acts as a diode, so when the LED is off, the I/O  $V_{IN}$  is about 1.2 V less than  $V_{CC}$ . The  $\Delta I_{CC}$  parameter in the [Electrical Characteristics](#) table shows how  $I_{CC}$  increases as  $V_{IN}$  becomes lower than  $V_{CC}$ . Designs that must minimize current consumption, such as battery power applications, must consider maintaining the I/O pins greater than or equal to  $V_{CC}$  when the LED is off.

[Figure 32](#) shows a high-value resistor in parallel with the LED. [Figure 33](#) shows  $V_{CC}$  less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O  $V_{IN}$  at or above  $V_{CC}$  and prevent additional supply current consumption when the LED is off.

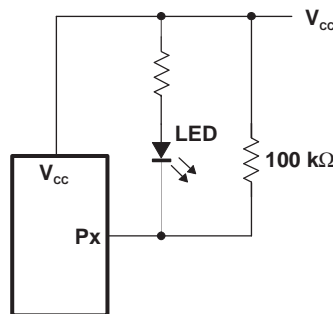
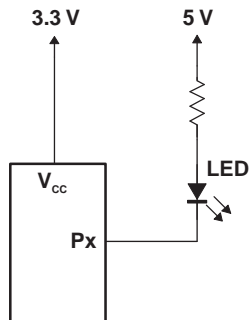


Figure 32. High-Value Resistor in Parallel With LED

## Typical Application (continued)



**Figure 33. Device Supplied by a Low Voltage**

### 9.2.2 Detailed Design Procedure

The pull-up resistors,  $R_p$ , for the SCL and SDA lines need to be selected appropriately and take into consideration the total capacitance of all slaves on the I<sup>2</sup>C bus. The minimum pull-up resistance is a function of  $V_{CC}$ ,  $V_{OL(max)}$ , and  $I_{OL}$  as shown in Equation 5.

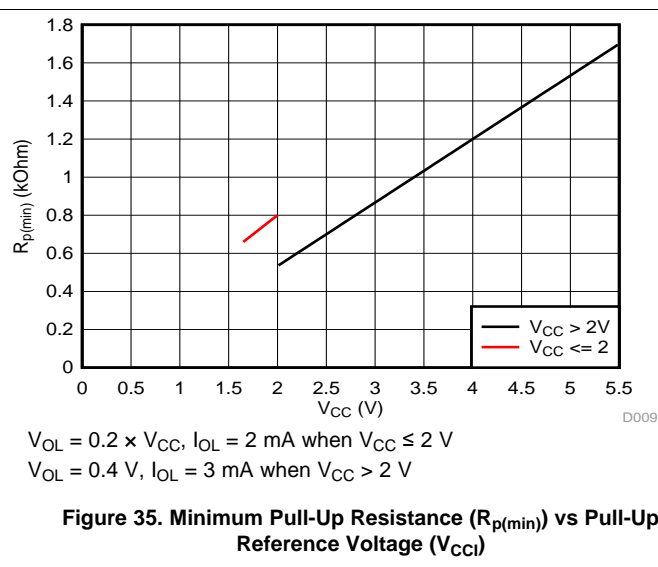
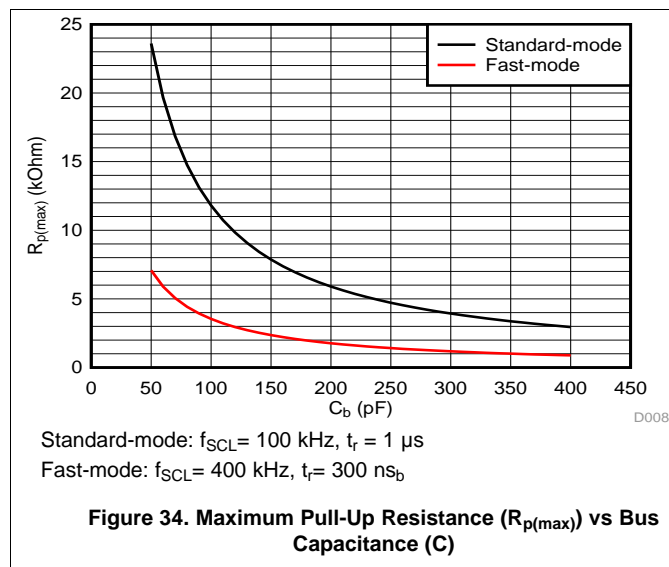
$$R_{p(min)} = \frac{V_{CC} - V_{OL(max)}}{I_{OL}} \quad (5)$$

The maximum pull-up resistance is a function of the maximum rise time,  $t_r$  (300 ns for fast-mode operation,  $f_{SCL} = 400$  kHz) and bus capacitance,  $C_b$  as shown in Equation 6.

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (6)$$

The maximum bus capacitance for an I<sup>2</sup>C bus must not exceed 400 pF for standard-mode or fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the TCA6408A-Q1,  $C_i$  for SCL or  $C_{i0}$  for SDA, the capacitance of wires, connections, traces, and the capacitance of additional slaves on the bus.

### 9.2.3 Application Curves



## 10 Power Supply Recommendations

### 10.1 Power-On Reset Requirements

In the event of a glitch or data corruption, TCA6408A-Q1 can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

The two types of power-on reset are shown in [Figure 36](#) and [Figure 37](#).

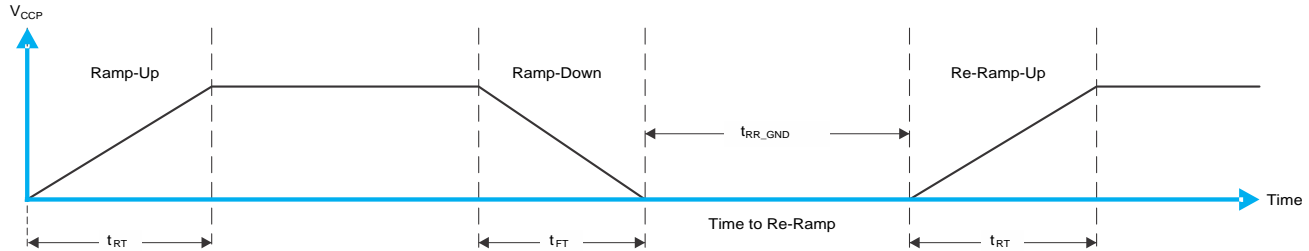


Figure 36. V<sub>CCP</sub> is Lowered Below 0.2 V and then Ramped Up to V<sub>CCP</sub>

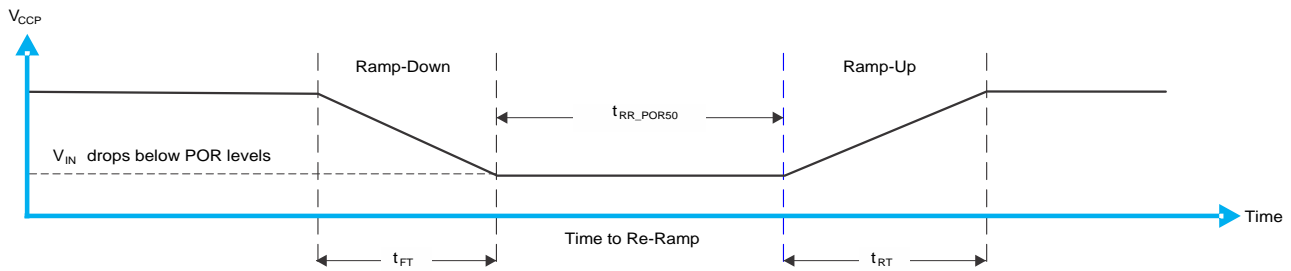


Figure 37. V<sub>CCP</sub> is Lowered Below the POR Threshold, then Ramped Back Up to V<sub>CCP</sub>

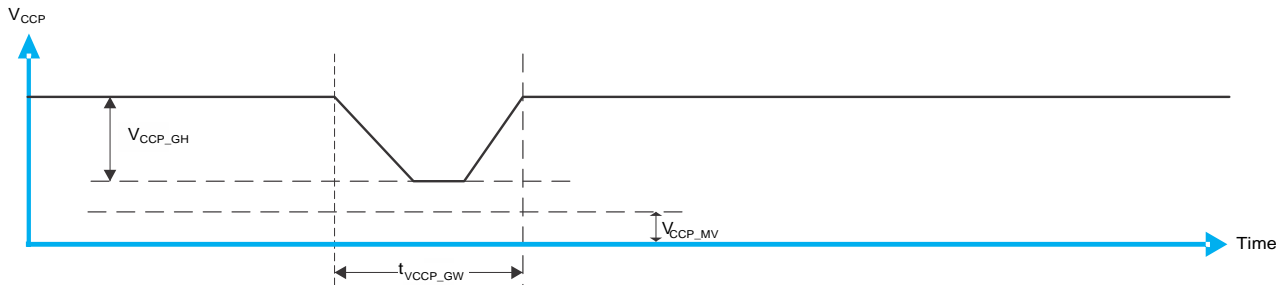
[Table 9](#) specifies the performance of the power-on reset feature for TCA6408A-Q1 for both types of power-on reset.

Table 9. Recommended Supply Sequencing and Ramp Rates at T<sub>A</sub> = 25°C<sup>(1)</sup>

PARAMETER			MIN	TYP	MAX	UNIT
t <sub>FT</sub>	Fall rate	See <a href="#">Figure 36</a>	0.1		2000	ms
t <sub>RT</sub>	Rise rate	See <a href="#">Figure 36</a>	0.1		2000	ms
t <sub>RR_GND</sub>	Time to re-ramp (when V <sub>CCP</sub> drops to GND)	See <a href="#">Figure 36</a>	1			μs
t <sub>RR_POR50</sub>	Time to re-ramp (when V <sub>CCP</sub> drops to V <sub>POR_MIN</sub> – 50 mV)	See <a href="#">Figure 37</a>	1			μs
V <sub>CCP_GH</sub>	Level that V <sub>CCP</sub> can glitch down from V <sub>CCP</sub> , but not cause a functional disruption when t <sub>VCCP_GW</sub> = 1 μs	See <a href="#">Figure 38</a>			1.2	V
V <sub>CCP_MV</sub>	The minimum voltage that VCC can glitch down to without causing a reset (V <sub>CC_GH</sub> must not be violated)	See <a href="#">Figure 38</a>	1.5			V
t <sub>VCCP_GW</sub>	Glitch width that does not cause a functional disruption when t <sub>VCCP_GH</sub> = 0.5 × V <sub>CCx</sub>	See <a href="#">Figure 38</a>			10	μs
V <sub>PORF</sub>	Voltage trip point of POR on falling V <sub>CCP</sub>		0.6	1		V
V <sub>PORR</sub>	Voltage trip point of POR on rising V <sub>CCP</sub>			1.2	1.5	V

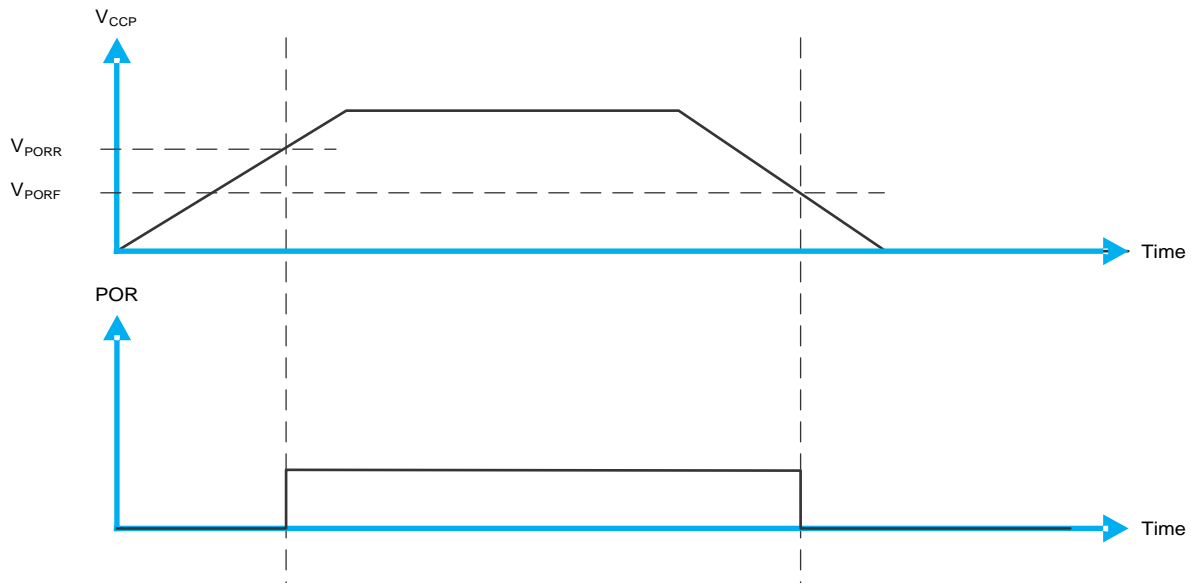
(1) Not tested. Specified by design.

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width ( $t_{V_{CCP\_GW}}$ ) and height ( $V_{CCP\_GH}$ ) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. [Figure 38](#) and [Table 9](#) provide more information on how to measure these specifications.



**Figure 38. Glitch Width and Glitch Height**

$V_{POR}$  is critical to the power-on reset.  $V_{PORR} / V_{PORF}$  is the voltage level at which the reset condition is released/asserted and all the registers and the I<sup>2</sup>C/SMBus state machine are initialized to their default states (upon a release of a reset condition). The voltage that the device has a reset condition asserted or released differs based on whether  $V_{CCP}$  is being lowered to or from 0. [Figure 39](#) and [Table 9](#) provide more details on this specification.



**Figure 39. Power On Reset**

## 11 Layout

### 11.1 Layout Guidelines

For printed circuit board (PCB) layout of the TCA6408A-Q1, common PCB layout practices must be followed, but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I<sup>2</sup>C signal speeds.

In all PCB layouts, it is a best practice to avoid right angles in signal traces, to fan out signal traces away from each other upon leaving the vicinity of an integrated circuit (IC), and to use thicker trace widths to carry higher amounts of current that commonly pass through power and ground traces. By-pass and de-coupling capacitors are commonly used to control the voltage on the V<sub>CCI</sub> and V<sub>CCP</sub> pins, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple. These capacitors must be placed as close to the TCA6408A-Q1 as possible. These best practices are shown in [Layout Example](#).

For the layout example provided in [Layout Example](#), it is possible to fabricate a PCB with only 2 layers by using the top layer for signal routing and the bottom layer as a split plane for power (V<sub>CCI</sub> and V<sub>CCP</sub>) and ground (GND). However, a 4-layer board is preferable for boards with higher density signal routing. On a 4-layer PCB, it is common to route signals on the top and bottom layer, dedicate one internal layer to a ground plane, and dedicate the other internal layer to a power plane. In a board layout using planes or split planes for power and ground, vias are placed directly next to the surface mount component pad which needs to attach to V<sub>CCI</sub>, V<sub>CCP</sub>, or GND and the via is connected electrically to the internal layer or the other side of the board. Vias are also used when a signal trace needs to be routed to the opposite side of the board, but this technique is not demonstrated in [Layout Example](#).

### 11.2 Layout Example

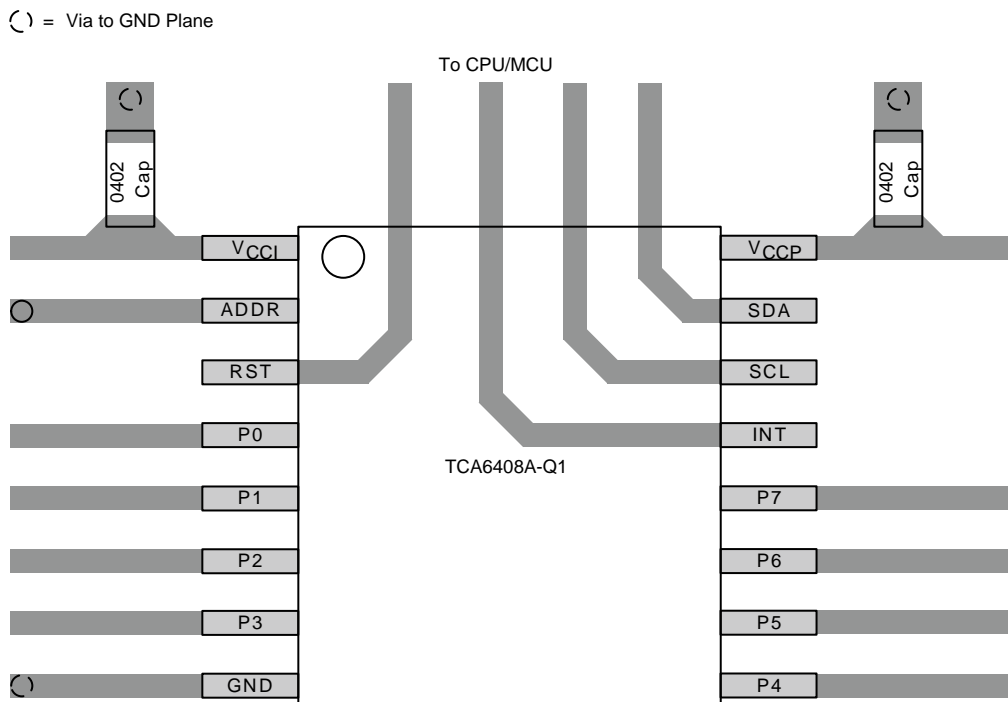


Figure 40. Example Layout (PW Package)

## 12 器件和文档支持

### 12.1 接收文档更新通知

如需接收文档更新通知，请访问 [ti.com](http://ti.com) 上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查阅已修订文档中包含的修订历史记录。

### 12.2 社区资源

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 12.5 Glossary

**SLYZ022** — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.



### 13 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏

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放大器和线性器件	<a href="http://www.ti.com.cn/amplifiers">www.ti.com.cn/amplifiers</a>	计算机及周边	<a href="http://www.ti.com.cn/computer">www.ti.com.cn/computer</a>
数据转换器	<a href="http://www.ti.com.cn/dataconverters">www.ti.com.cn/dataconverters</a>	消费电子	<a href="http://www.ti.com.cn/consumer-apps">www.ti.com.cn/consumer-apps</a>
DLP® 产品	<a href="http://www.dlp.com">www.dlp.com</a>	能源	<a href="http://www.ti.com.cn/energy">www.ti.com.cn/energy</a>
DSP - 数字信号处理器	<a href="http://www.ti.com.cn/dsp">www.ti.com.cn/dsp</a>	工业应用	<a href="http://www.ti.com.cn/industrial">www.ti.com.cn/industrial</a>
时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
接口	<a href="http://www.ti.com.cn/interface">www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
逻辑	<a href="http://www.ti.com.cn/logic">www.ti.com.cn/logic</a>	汽车电子	<a href="http://www.ti.com.cn/automotive">www.ti.com.cn/automotive</a>
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RFID 系统	<a href="http://www.ti.com.cn/rfidsys">www.ti.com.cn/rfidsys</a>		
OMAP应用处理器	<a href="http://www.ti.com/omap">www.ti.com/omap</a>		
无线连通性	<a href="http://www.ti.com.cn/wirelessconnectivity">www.ti.com.cn/wirelessconnectivity</a>	德州仪器在线技术支持社区	<a href="http://www.deyisupport.com">www.deyisupport.com</a>

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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TCA6408AQPWRQ1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	6408AQ	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

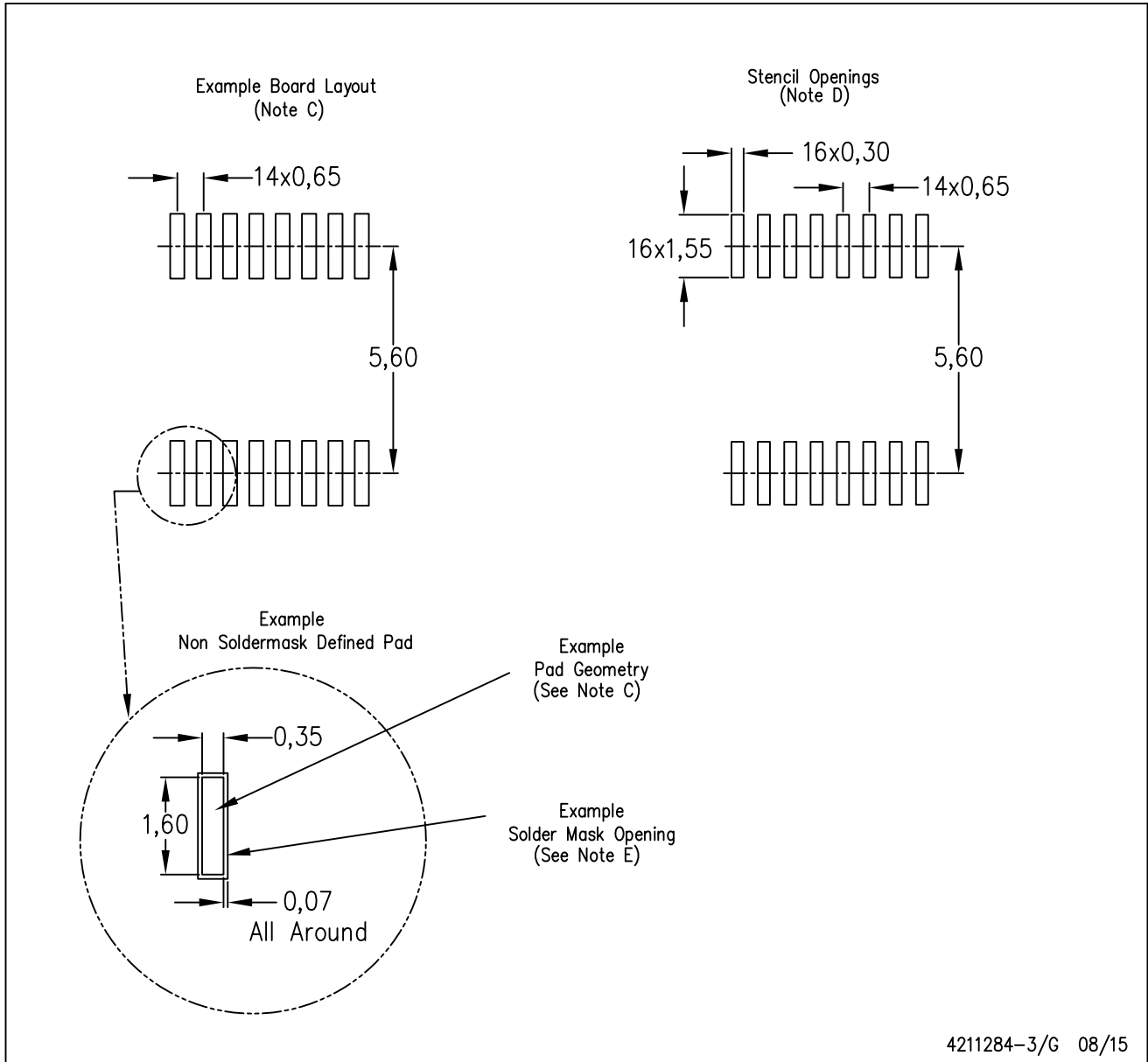


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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接口	<a href="http://www.ti.com.cn/interface">www.ti.com.cn/interface</a>	安防应用	<a href="http://www.ti.com.cn/security">www.ti.com.cn/security</a>
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